



BGA/CSP DEVELOPMENT UPDATE SERVICE

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The third quarterly BGA/CSP update for 2001 features trends in area array packages for network and workstation/server applications. New products containing CSPs and wafer level packages are introduced, including Casio's color wristwatch/camera, Ericsson's Bluetooth™ phone, and Handspring's Visor Edge PDA. A special report on the capacity for PBGA and CSP assembly worldwide provides insight into the current economic situation. The report provides a review of flip chip substrate suppliers and discusses flip chip bumping of ICs fabricated with copper instead of aluminum wiring. New CSP and BGA packages from IBM, Intel, and Texas Instruments are highlighted.

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